

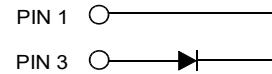
## High Temperature Silicon Carbide Power Schottky Diode

### Features

- 650 V Schottky rectifier
- 210 °C maximum operating temperature
- Zero reverse recovery charge
- Superior surge current capability
- Positive temperature coefficient of  $V_F$
- Temperature independent switching behavior
- Lowest figure of merit  $Q_c/I_F$
- Available screened to Mil-PRF-19500

$V_{RRM}$	=	650 V
$I_F (T_c=25^\circ C)$	=	45 A
$Q_c$	=	66 nC

### Package



**SMD0.5 / TO – 276 (Hermetic Package)**

### Advantages

- High temperature operation
- Improved circuit efficiency (Lower overall cost)
- Low switching losses
- Ease of paralleling devices without thermal runaway
- Smaller heat sink requirements
- Industry's lowest reverse recovery charge
- Industry's lowest device capacitance
- Ideal for output switching of power supplies
- Best in class reverse leakage current at operating temperature

### Applications

- Down Hole Oil Drilling
- Geothermal Instrumentation
- Solenoid Actuators
- General Purpose High-Temperature Switching
- Amplifiers
- Solar Inverters
- Switched-Mode Power Supply (SMPS)
- Power Factor Correction (PFC)

### Maximum Ratings at $T_j = 210^\circ C$ , unless otherwise specified

Parameter	Symbol	Conditions	Values	Unit
Repetitive peak reverse voltage	$V_{RRM}$		650	V
Continuous forward current	$I_F$	$T_c = 25^\circ C$	45	A
Continuous forward current	$I_F$	$T_c \leq 190^\circ C$	14.6	A
RMS forward current	$I_{F(RMS)}$	$T_c \leq 190^\circ C$	26	A
Surge non-repetitive forward current, Half Sine Wave	$I_{F,SM}$	$T_c = 25^\circ C, t_p = 10 \text{ ms}$	140	A
Non-repetitive peak forward current	$I_{F,max}$	$T_c = 25^\circ C, t_p = 10 \mu\text{s}$	650	A
$I^2t$ value	$\int I^2 dt$	$T_c = 25^\circ C, t_p = 10 \text{ ms}$	98	$\text{A}^2\text{s}$
Power dissipation	$P_{tot}$	$T_c = 25^\circ C$	453	W
Operating and storage temperature	$T_j, T_{stg}$		-55 to 210	$^\circ C$

### Electrical Characteristics at $T_j = 210^\circ C$ , unless otherwise specified

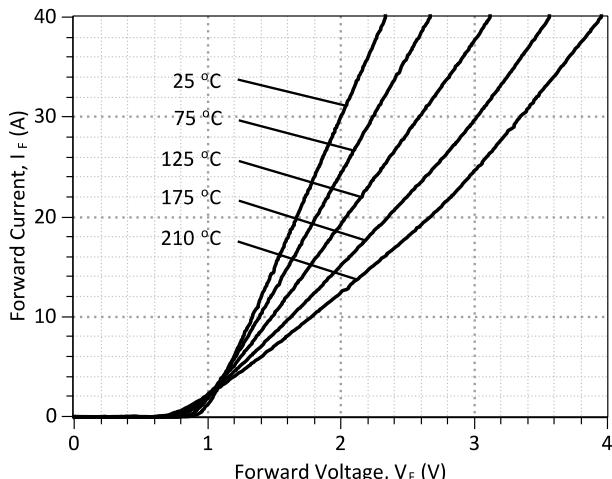
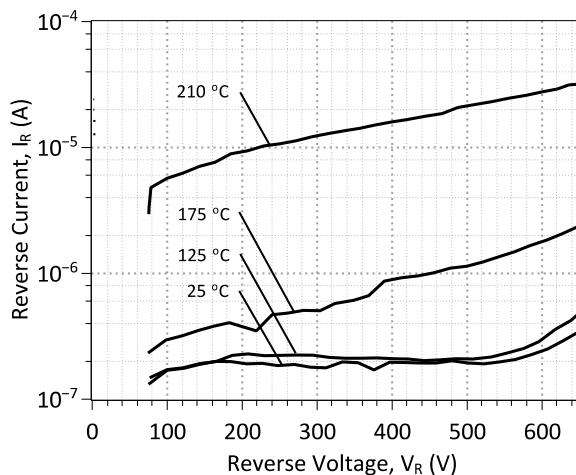
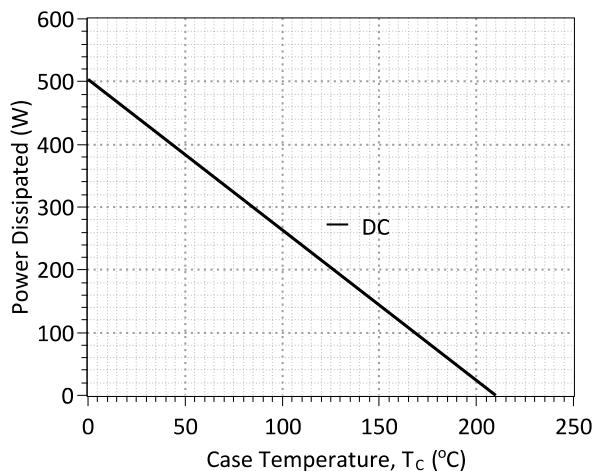
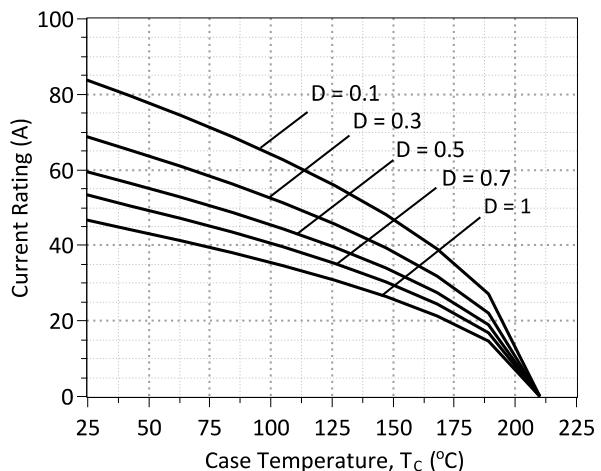
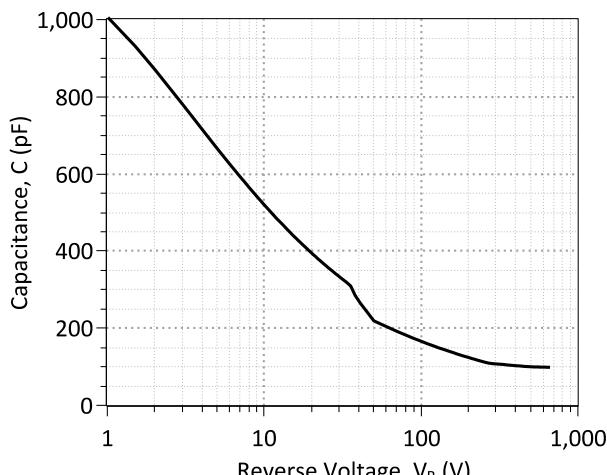
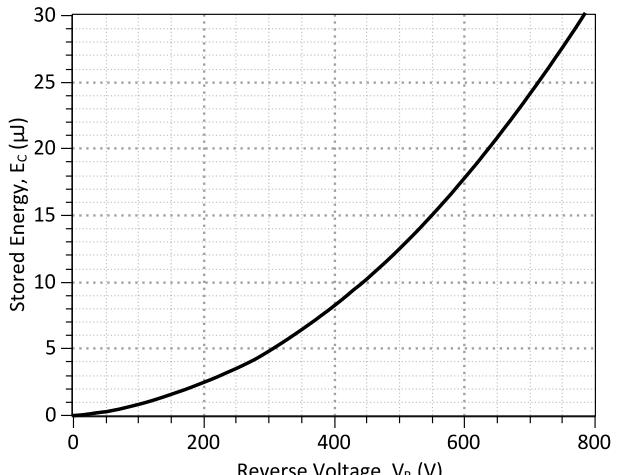
Parameter	Symbol	Conditions	Values			Unit
			min.	typ.	max.	
Diode forward voltage	$V_F$	$I_F = 15 \text{ A}, T_j = 25^\circ C$	1.5	2.2		V
		$I_F = 15 \text{ A}, T_j = 210^\circ C$	2.2			
Reverse current	$I_R$	$V_R = 650 \text{ V}, T_j = 25^\circ C$	1	50	200	$\mu\text{A}$
		$V_R = 650 \text{ V}, T_j = 210^\circ C$	50			
Total capacitive charge	$Q_c$	$I_F \leq I_{F,MAX}$	66			nC
Switching time	$t_s$	$dI_F/dt = 200 \text{ A}/\mu\text{s}$	1107	< 49		ns
		$T_j = 210^\circ C$	< 49			
Total capacitance	$C$	$V_R = 1 \text{ V}, f = 1 \text{ MHz}, T_j = 25^\circ C$	1107	103	99	pF
		$V_R = 400 \text{ V}, f = 1 \text{ MHz}, T_j = 25^\circ C$	103			
		$V_R = 650 \text{ V}, f = 1 \text{ MHz}, T_j = 25^\circ C$	99			

### Thermal Characteristics

Thermal resistance, junction - case	$R_{thJC}$	0.49	$^\circ C/W$
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### Mechanical Properties

Mounting torque	M	0.6	Nm
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**Figure 1: Typical Forward Characteristics**

**Figure 2: Typical Reverse Characteristics**

**Figure 3: Power Derating Curve**

**Figure 4: Current Derating Curves ( $D = t_p/T$ ,  $t_p = 400 \mu s$ )  
(Considering worst case  $Z_{th}$  conditions )**

**Figure 5: Typical Junction Capacitance vs Reverse Voltage Characteristics**

**Figure 6: Typical Capacitive Energy vs Reverse Voltage Characteristics**

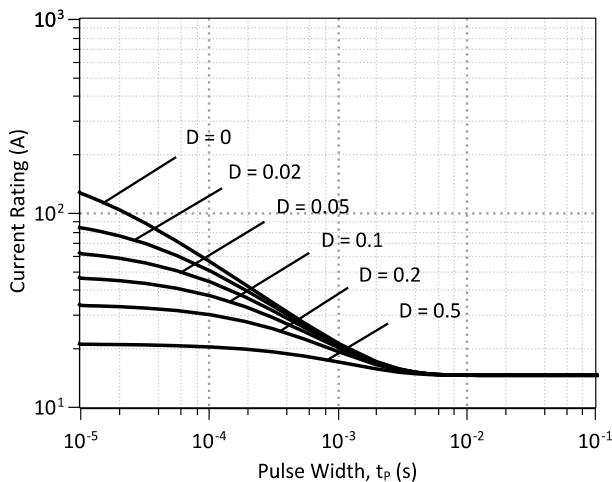


Figure 7: Current vs Pulse Duration Curves at  $T_c = 190 \text{ } ^\circ\text{C}$

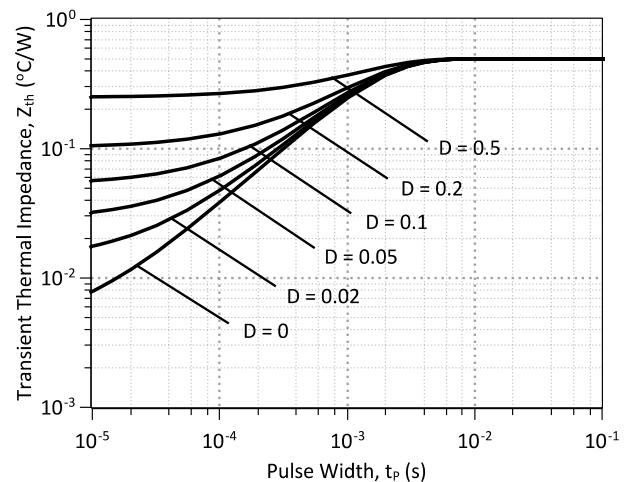
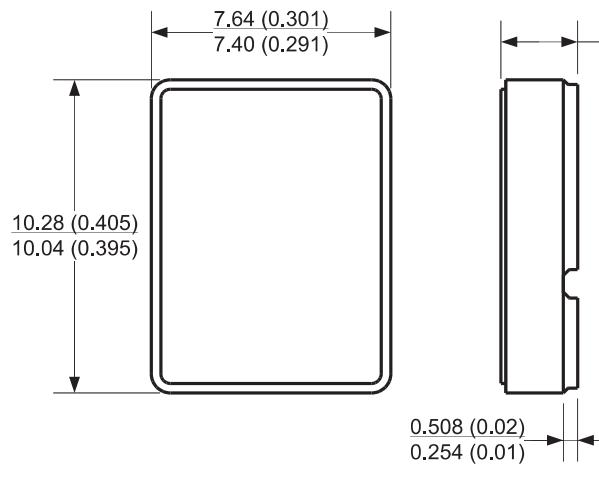


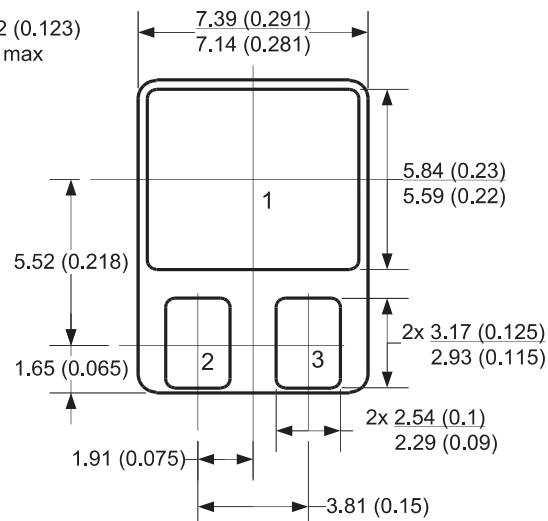
Figure 8: Transient Thermal Impedance

### Package Dimensions:

**SMD-0.5/TO-276**



**PACKAGE OUTLINE**



**NOTE**

1. CONTROLLED DIMENSION IS INCH. DIMENSION IN BRACKET IS MILLIMETER.
2. DIMENSIONS DO NOT INCLUDE END FLASH, MOLD FLASH, MATERIAL PROTRUSIONS

<b>Revision History</b>			
Date	Revision	Comments	Supersedes
2014/08/26	1	Updated Electrical Characteristics	
2012/04/24	0	Initial release	

## Published by

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## SPICE Model Parameters

Copy the following code into a SPICE software program for simulation of the 1N8035-GA device.

```
* MODEL OF GeneSiC Semiconductor Inc.  
*  
* $Revision: 1.0      $  
* $Date: 05-SEP-2013 $  
*  
* GeneSiC Semiconductor Inc.  
* 43670 Trade Center Place Ste. 155  
* Dulles, VA 20166  
* http://www.genesicsemi.com/index.php/hit-sic/schottky  
*  
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* These models are provided "AS IS, WHERE IS, AND WITH NO WARRANTY  
* OF ANY KIND EITHER EXPRESSED OR IMPLIED, INCLUDING BUT NOT LIMITED  
* TO ANY IMPLIED WARRANTIES OF MERCHANTABILITY AND FITNESS FOR A  
* PARTICULAR PURPOSE."  
* Models accurate up to 2 times rated drain current.  
*  
* Start of 1N8035-GA SPICE Model  
*.SUBCKT 1N8035 ANODE KATHODE  
D1 ANODE KATHODE 1N8035_25C; Call the Schottky Diode Model  
D2 ANODE KATHODE 1N8035_PIN; Call the PiN Diode Model  
.MODEL 1N8035_25C D  
+ IS      8.46E-17      RS      0.0319  
+ N       1              IKF     1000  
+ EG      1.2            XTI     3  
+ TRS1    0.0038        TRS2    3.00E-05  
+ CJO     1.26E-09      VJ      0.438  
+ M       1.5278         FC      0.5  
+ TT      1.00E-10       BV      650  
+ IBV    1.00E-03        VPK     650  
+ IAVE    20             TYPE    Sic_Schottky  
+ MFG     GeneSiC_Semiconductor  
.MODEL 1N8035_PIN D  
+ IS      2.77E-10      RS      0.086693  
+ N       3.3505         IKF    3.67E-06  
+ EG      3.23            XTI   -10  
+ FC      0.5            TT      0  
+ BV      650             IBV   1.00E-03  
+ VPK    650             IAVE   20  
+ TYPE   Sic_Pin  
.ENDS  
*  
* End of 1N8035-GA SPICE Model
```

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